


**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCN No.</b>	ADG/19/11667	
<b>1.3 Title of PCN</b>	TO-3P new molding compound - SP Semiconductor (Korea)	
<b>1.4 Product Category</b>	IGBTs / Power BIPOLAR	
<b>1.5 Issue date</b>	2019-07-11	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	ROBERTSON HEATHER
<b>2.1.2 Phone</b>	+1 8475853058
<b>2.1.3 Email</b>	heather.robertson@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Angelo RAO
<b>2.1.2 Marketing Manager</b>	Natale Sandro D'ANGELO
<b>2.1.3 Quality Manager</b>	Vincenzo MILITANO

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Materials	New direct material part number (same supplier, different supplier or new supplier), Lead frame base material	SP Semiconductor (Korea)

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	TO-3P of Subcontractor SP Semiconductor (Korea) are manufactured with SI-7200DX2 molding compound.	TO-3P of Subcontractor SP Semiconductor (Korea) will be manufactured with KTMC-1050GR molding compound.
<b>4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?</b>	no impact	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	Samsung SDI production discontinuation
<b>5.2 Customer Benefit</b>	CAPACITY INCREASE

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	by FG code and Q.A. number
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2019-07-05
<b>7.2 Intended start of delivery</b>	2019-10-05
<b>7.3 Qualification sample available?</b>	Upon Request

**8. Qualification / Validation**

<b>8.1 Description</b>	11667 Rel15-2019.pdf		
<b>8.2 Qualification report and qualification results</b>	Available (see attachment)	<b>Issue Date</b>	2019-07-11

**9. Attachments (additional documentations)**

11667 Public product.pdf  
11667 TO-3P New Molding compound - SP Semi (Korea).pdf  
11667 Rel15-2019.pdf

**10. Affected parts**

10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	2SD1047	
	STGWT15H60F	
	STGWT20H65FB	
	STGWT20IH125DF	
	STGWT20V60DF	
	STGWT28IH125DF	
	STGWT30H60DFB	
	STGWT30H65FB	
	STGWT30V60DF	
	STGWT40H65DFB	
	STGWT40HP65FB	
	STGWT40V60DF	
	STGWT60H60DLFB	
	STGWT60H65DFB	
	STGWT60H65FB	
	STGWT60V60DF	
	STGWT80H65DFB	
	STGWT80H65FB	
	STGWT80V60DF	
	STGWT80V60F	
	TIP35CP	



## Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

**PCN Title :** TO-3P new molding compound - SP Semiconductor (Korea)

**PCN Reference :** ADG/19/11667

**Subject :** Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STGWT30HP65FB	STGWT30H60DFB	STGWT80H65FB
STGWT60H65FB	STGWT28IH125DF	STGWT20HP65FB
STGWT40HP65FB	STGWT30V60DF	STGWT40V60DF
2SD1047	STGWT60H60DLFB	STGWT40H65DFB
STGWT20IH125DF	STGWT15H60F	STGWT20H65FB
STGWT80V60DF	STGWT20V60DF	STGWT20H60DF
STGWT30H65FB	STGWT60H65DFB	TIP35CP
STGWT80H65DFB	STGWT30V60F	STGWT20V60F
STGWT60V60DF	STGWT80V60F	



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